

# MECHANICAL CASE OUTLINE

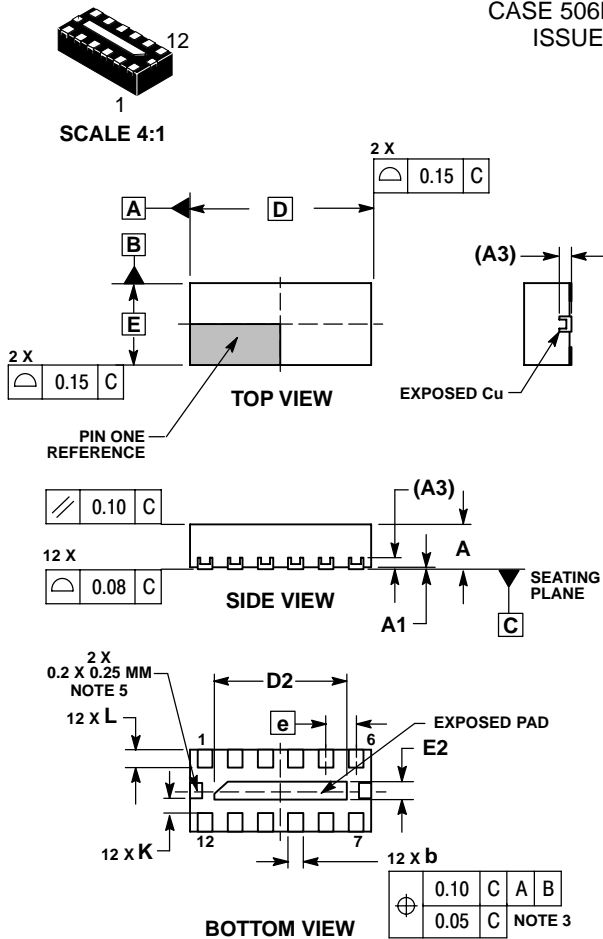
## PACKAGE DIMENSIONS

ON Semiconductor®



WDFN12, 3.0x1.35x0.75  
CASE 506BB-01  
ISSUE O

DATE 26 JUL 2006

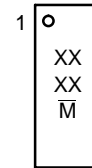


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. EXPOSED PADS CONNECTED TO DIE FLAG. USED AS TEST CONTACTS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.18	0.30
D	3.00	BSC
D2	2.10	2.30
E	1.35	BSC
E2	0.20	0.40
e	0.50	BSC
K	0.20	---
L	0.20	0.40

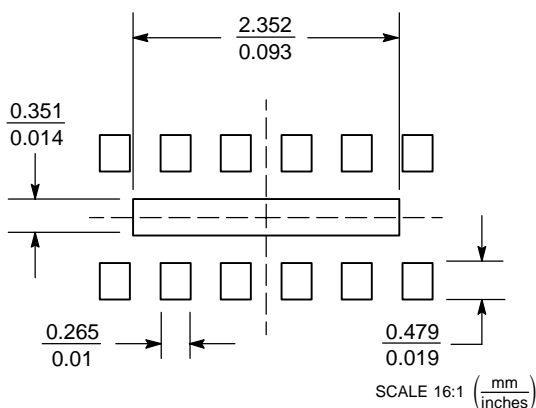
### GENERIC MARKING DIAGRAM\*



- XXXX = Specific Device Code
- M̄ = Month
- G or ■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLE 1:

- PIN 1. ANODE 1
- 2. ANODE 2
- 3. ANODE 3
- 4. ANODE 4
- 5. ANODE 5
- 6. ANODE 6
- 7. ANODE 7
- 8. ANODE 8
- 9. ANODE 9
- 10. ANODE 10
- 11. ANODE 11
- 12. ANODE 12

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WDFN12, 3.0x1.35x0.75, 0.5 MM PITCH	PAGE 1 OF 2

